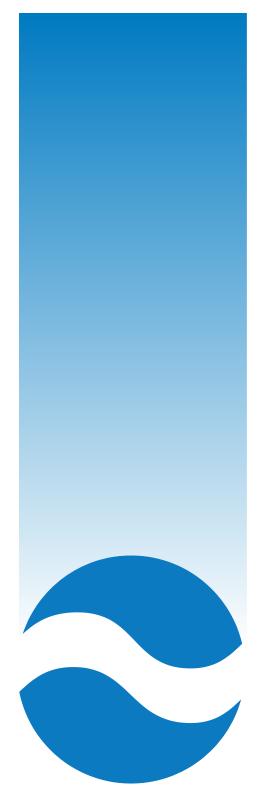
# IPC/JEDEC J-STD-033D April 2018

Supersedes IPC/JEDEC J-STD-033C-1 August 2014

# JOINT INDUSTRY STANDARD

Handling, Packing, Shipping and Use of Moisture, Reflow, and Process Sensitive Devices





Copyright Association Connecting Electronics Industries

#### Notice

JEDEC and IPC Standards and Publications are designed to serve the public interest through eliminating misunderstandings between manufacturers and purchasers, facilitating interchangeability and improvement of products, and assisting the purchaser in selecting and obtaining with minimum delay the proper product for his particular need. Existence of such Standards and Publications shall not in any respect preclude any member or nonmember of JEDEC or IPC from manufacturing or selling products not conforming to such Standards and Publications, nor shall the existence of such Standards and Publications preclude their voluntary use by those other than JEDEC and IPC members, whether the standard is to be used either domestically or internationally.

Recommended Standards and Publications are adopted by JEDEC and IPC without regard to whether their adoption may involve patents on articles, materials, or processes. By such action, JEDEC and IPC do not assume any liability to any patent owner, nor do they assume any obligation whatever to parties adopting the Recommended Standard or Publication. Users are also wholly responsible for protecting themselves against all claims of liabilities for patent infringement.

The material in this joint standard was developed by the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the IPC Plastic Chip Carrier Cracking Task Group (B-10a)

For Technical Information Contact:

Tel 703 907.0026

Fax 703 907.7501

## JEDEC Solid State Technology Association 3103 North 10th Street, Suite 240-S Arlington, VA 22201-2107

#### IPC

3000 Lakeside Drive, Suite 105N Bannockburn, Illinois 60015-1249 Tel 847 615.7100 Fax 847 615.7105

Please use the Standard Improvement Form shown at the end of this document.

©Copyright 2018. JEDEC Solid State Technology Association, Arlington, Virginia, and IPC, Bannockburn, Illinois, USA. All rights reserved under both international and Pan-American copyright conventions. *Any copying, scanning or other reproduction of these materials without the prior written consent of the copyright holder is strictly prohibited and constitutes infringement under the Copyright Law of the United States.* 



IPC/JEDEC J-STD-033D



Handling, Packing, Shipping and Use of Moisture, Reflow, and Process Sensitive Devices

A joint standard developed by the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the B-10a Plastic Chip Carrier Cracking Task Group of IPC

#### Supersedes:

IPC/JEDEC J-STD-033C-1 -August 2014 IPC/JEDEC J-STD-033C -February 2012 IPC/JEDEC J-STD-033B.1 includes Amendment 1 -January 2007 IPC/JEDEC J-STD-033B -October 2005 IPC/JEDEC J-STD-033A -July 2002 IPC/JEDEC J-STD-033 -April 1999 **JEDEC JEP124** IPC-SM-786A -January 1995 IPC-SM-786 - December 1990

Users of this publication are encouraged to participate in the development of future revisions.

Contact:

### JEDEC

#### Solid State Technology Association 3103 North 10th Street, Suite 240-S Arlington, VA 22201-2107

Arlington, VA 22201-2107 Tel 703 907.0026 Fax 703 907.7501 IPC

3000 Lakeside Drive, Suite 105 N Bannockburn, Illinois 60015-1249 Tel 847 615.7100 Fax 847 615.7105